ASSOCIATION CONNECTING ELECTROMICS INDUSTRIES® International and Pa	IPC. Bannockl	burn, Illinois, A	Il rights reserved untions.	under both	This docume level parts, t	ent is a declarati he declaration e	on of the su	bstances v all lower	vithin the manufactu level materials for v	rer listed in the rest of the	tem. Note: nanufacture	if the item is an as r has engineering	sembly with low responsibility.	
	21.1 IPC Web Site for Information on IPC-1752 Standard Form http://www.ipc.org/IPC-175x Dist				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and M					lfg Informa	ion			
Supplier Information														
Company name* Company			ıy unique ID			Unique ID Authority				Respon	Response Date*			
nsemi											2025-05-12			
ntact Name Title - Contact			ct	Phone - Contact			ct* Ema			Email -	mail - Contact*			
Product-Env-Stewards Product Envir			nviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Authorized Representative* Title - Repres			esentative			Phone - Representative*				Email - Representative*				
Product-Env-Stewards Product Env			Enviro Compliance			NA				Produe	Product-Env-Stewards@onsemi.com			
Requester Item Number	Mfr Iten	n Number	Mfr Item Name			Effective Date	Version	М	Manufacturing Site		Weight*	UOM	Unit Type	
	FDPC80	PPC8012S PT8N 25/12 & PT		'8N 25/12 S		2025-05-12		PI	РВВ		70.636	mg	Each	
Anufacturing Proccess Inform	ation												I	
Terminal Plating / Grid Array M	Iaterial 7	al Terminal Base Alloy		J-STD-020 MSI	MSL Rating Pe		ak Process Body Temperature Max Time at Pe		Max Time at Peal	Tempera	ture Num	ber of Reflow Cyd	les	
Matte Tin (Sn) - annealed CU Alloy		CU Alloy		1		260		С	30	secor	nds 3			
omments														
vel 1 - maximum time at peak tempera	ture during so	dering is 10-3	0 seconds											
or more information regarding materia	l composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company that agreement, will be the sole and exclusive	lease indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, admium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part oncompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, so for the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. If a homogeneous material within the part of the date that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not idependently verified information provided by others, Supplier agrees that, at a minimum, itsuppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the ertification in the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the arranty rights and/or remedies of Supplier's Standard Terms andConditions of Sale applicable to such part shall apply.										
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).								
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the						
Supplier Digital Signature	astislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	8.097	mg	Supplier	Zinc (Zn)	7440-66-6		0.0097	mg
			Supplier	Iron (Fe)	7439-89-6		0.1903	mg
			Supplier	Copper (Cu)	7440-50-8		7.8946	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0024	mg
Die	0.99	mg	Supplier	Silicon (Si)	7440-21-3		0.99	mg
Lead Frame	20.211	mg	Supplier	Zinc (Zn)	7440-66-6		0.0243	mg
			Supplier	Iron (Fe)	7439-89-6		0.475	mg
			Supplier	Copper (Cu)	7440-50-8		19.7057	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0061	mg
Mold Compound-Black	14.236	mg		Epoxy resin	proprietary data		1.8934	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0285	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		12.3141	mg
Plating	25.1	mg	Supplier	Tin (Sn)	7440-31-5		25.1	mg
Solder Paste	1.989	mg	Supplier	Silver (Ag)	7440-22-4		0.0497	mg
			А	Lead (Pb)	7439-92-1	7a	1.8398	mg
			Supplier	Tin (Sn)	7440-31-5		0.0994	mg
Wire Bond - Cu	0.013	mg	Supplier	Palladium (Pd)	7440-05-3		0.0002	mg
			Supplier	Gold (Au)	7440-57-5		0	mg
			Supplier	Copper (Cu)	7440-50-8		0.0128	mg